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Kind regards,

Team Nexperia

74HC4053-Q100; 74HCT4053-Q100
Triple 2-channel analog multiplexer/demultiplexer

Rev. 2 — 22 November 2012   **Product data sheet**

1. General description

The 74HC4053-Q100; 74HCT4053-Q100 is a high-speed Si-gate CMOS device and is pin compatible with Low-power Schottky TTL (LSTTL). It is specified in compliance with JEDEC standard no. 7A.

The 74HC4053-Q100; 74HCT4053-Q100 is triple 2-channel analog multiplexer/demultiplexer with a common enable input ($\overline{E}$). Each multiplexer/demultiplexer has two independent inputs/outputs (nY0 and nY1), a common input/output (nZ) and three digital select inputs (Sn). With $\overline{E}$ LOW, one of the two switches is selected (low-impedance ON-state) by S1 to S3. With $\overline{E}$ HIGH, all switches are in the high-impedance OFF-state, independent of S1 to S3.

V_{CC} and GND are the supply voltage pins for the digital control inputs (S0 to S2, and $\overline{E}$). The V_{CC} to GND ranges are 2.0 V to 10.0 V for 74HC4053-Q100, and 4.5 V to 5.5 V for 74HCT4053-Q100. The analog inputs/outputs (nY0 to nY1, and nZ) can swing between V_{CC} as a positive limit and V_{EE} as a negative limit. $V_{CC} - V_{EE}$ may not exceed 10.0 V.

For operation as a digital multiplexer/demultiplexer, V_{EE} is connected to GND (typically ground).

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

2. Features and benefits

- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
  - Specified from −40 °C to +85 °C and from −40 °C to +125 °C
- Wide analog input voltage range from −5 V to +5 V
- Low ON resistance:
  - 80 Ω (typical) at $V_{CC} - V_{EE}$ = 4.5 V
  - 70 Ω (typical) at $V_{CC} - V_{EE}$ = 6.0 V
  - 60 Ω (typical) at $V_{CC} - V_{EE}$ = 9.0 V
- Logic level translation: to enable 5 V logic to communicate with ±5 V analog signals
- Typical 'break before make' built-in
- ESD protection:
  - MIL-STD-883, method 3015 exceeds 2000 V
  - HBM JESD22-A114F exceeds 2000 V
  - MM JESD22-A115-A exceeds 200 V (C = 200 pF, R = 0 Ω)
  - CDM AEC-Q100-011 revision B exceeds 1000 V
- Multiple package options

3. Applications

- Analog multiplexing and demultiplexing
- Digital multiplexing and demultiplexing
- Signal gating

4. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	**Name**	**Description**	**Version**
74HC4053D-Q100 74HCT4053D-Q100	−40 °C to +125 °C	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
74HC4053PW-Q100 74HCT4053PW-Q100	−40 °C to +125 °C	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm	SOT403-1
74HC4053BQ-Q100 74HCT4053BQ-Q100	−40 °C to +125 °C	DHVQFN16	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 16 terminals; body 2.5 × 3.5 × 0.85 mm	SOT763-1

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5. Functional diagram
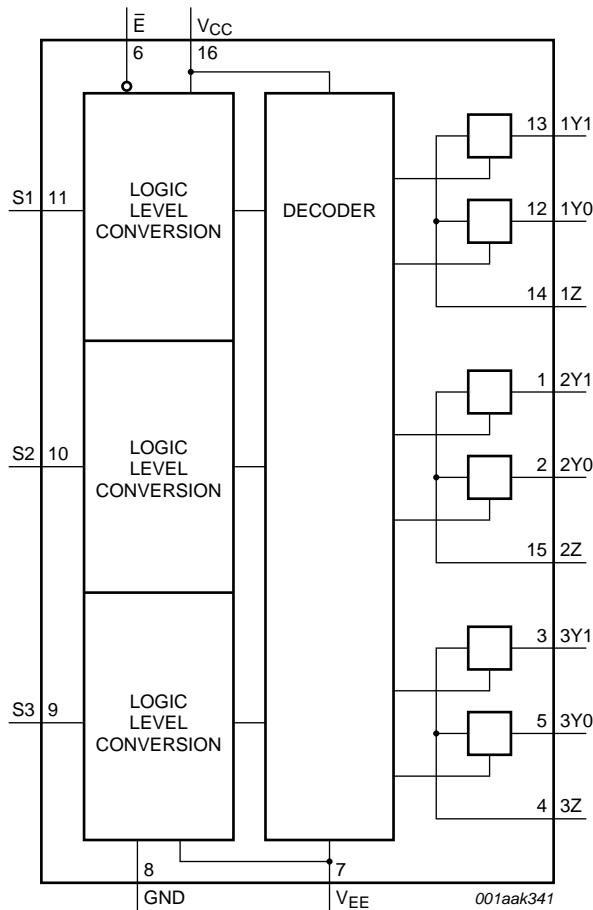
Fig 1.   Functional diagram
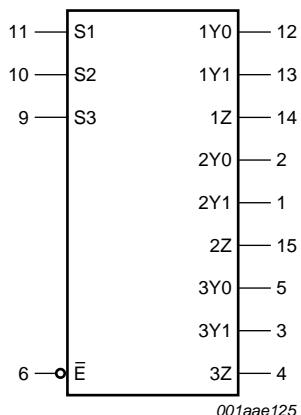
Fig 2.   Logic symbol
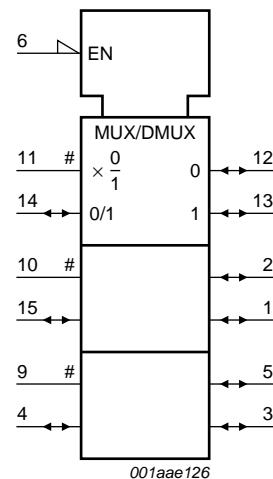
Fig 3.   IEC logic symbol
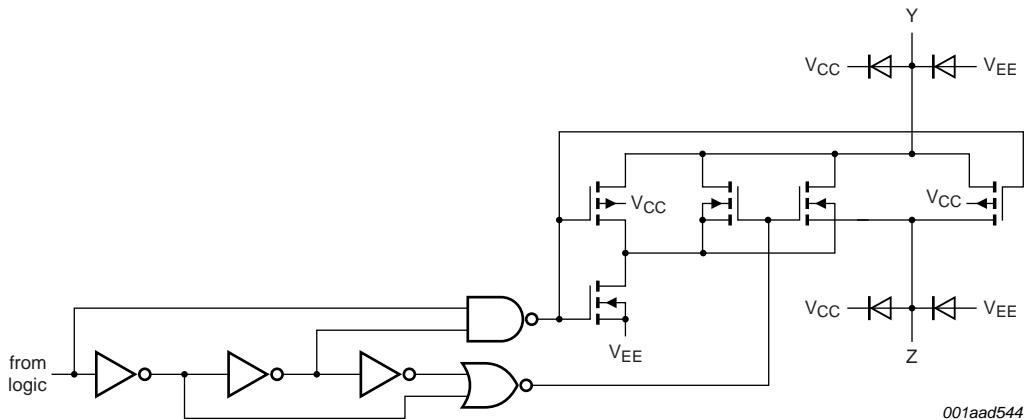
Fig 4. **Schematic diagram (one switch)**

6. Pinning information

6.1 Pinning
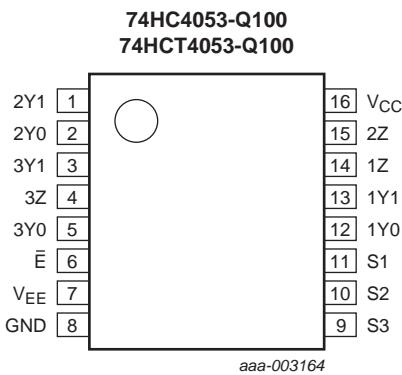
Fig 5. **Pin configuration SO16 and TSSOP16**
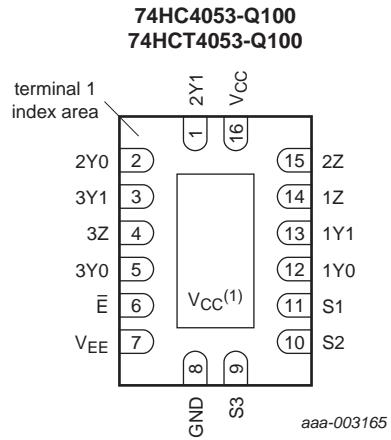
(1) This is not a supply pin. The substrate is attached to this pad using conductive die attach material. There is no electrical or mechanical requirement to solder this pad. However, if it is soldered, the solder land should remain floating or be connected to VCC.

Fig 6. **Pin configuration DHVQFN16**

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6.2 Pin description

Table 2.   Pin description

Symbol	Pin	Description
$\overline{E}$	6	enable input (active LOW)
V_{EE}	7	supply voltage
GND	8	ground supply voltage
S1, S2, S3	11, 10, 9	select input
1Y0, 2Y0, 3Y0	12, 2, 5	independent input or output
1Y1, 2Y1, 3Y1	13, 1, 3	independent input or output
1Z, 2Z, 3Z	14, 15, 4	common output or input
V_{CC}	16	supply voltage

7.   Functional description

Table 3.   Function table [1]

Inputs		Channel on
$\overline{E}$	Sn	
L	L	nY0 to nZ
L	H	nY1 to nZ
H	X	switches off

[1]   H = HIGH voltage level; L = LOW voltage level; X = don't care.

8.   Limiting values

Table 4.   Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to $V_{SS} = 0$ V (ground).

| Symbol	Parameter	Conditions		Min	Max	Unit
V_{CC}	supply voltage		[1]	−0.5	+11.0	V
I_{IK}	input clamping current	$V_I < -0.5$ V or $V_I > V_{CC} + 0.5$ V		-	±20	mA
I_{SK}	switch clamping current	$V_{SW} < -0.5$ V or $V_{SW} > V_{CC} + 0.5$ V		-	±20	mA
I_{SW}	switch current	-0.5 V $< V_{SW} < V_{CC} + 0.5$ V		-	±25	mA
I_{EE}	supply current			-	±20	mA
I_{CC}	supply current			-	50	mA
I_{GND}	ground current			-	−50	mA
T_{stg}	storage temperature			−65	+150	°C
P_{tot}	total power dissipation		[2]	-	500	mW
P	power dissipation	per switch		-	100	mW

[1]   To avoid drawing V_{CC} current out of terminal nZ, when switch current flows into terminals nYn, the voltage drop across the bidirectional switch must not exceed 0.4 V. If the switch current flows into terminal nZ, no V_{CC} current flows out of terminals nYn. In this case, there is no limit for the voltage drop across the switch, but the voltages at nYn and nZ may not exceed V_{CC} or V_{EE}.

[2]   For SO16 package: above 70 °C the value of P_{tot} derates linearly with 8 mW/K.
    For TSSOP16 package: above 60 °C the value of P_{tot} derates linearly with 5.5 mW/K.
    For DHVQFN16 package: above 60 °C the value of P_{tot} derates linearly with 4.5 mW/K.

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9. Recommended operating conditions

Table 5. **Recommended operating conditions**

Symbol	Parameter	Conditions	74HC4053-Q100			74HCT4053-Q100			Unit
			Min	**Typ**	**Max**	**Min**	**Typ**	**Max**	
V_{CC}	supply voltage	see Figure 7 and Figure 8							
		$V_{CC} - GND$	2.0	5.0	10.0	4.5	5.0	5.5	V
		$V_{CC} - V_{EE}$	2.0	5.0	10.0	2.0	5.0	10.0	V
V_I	input voltage		GND	-	V_{CC}	GND	-	V_{CC}	V
V_{SW}	switch voltage		V_{EE}	-	V_{CC}	V_{EE}	-	V_{CC}	V
T_{amb}	ambient temperature		−40	+25	+125	−40	+25	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	V_{CC} = 2.0 V	-	-	625	-	-	-	ns/V
		V_{CC} = 4.5 V	-	1.67	139	-	1.67	139	ns/V
		V_{CC} = 6.0 V	-	-	83	-	-	-	ns/V
		V_{CC} = 10.0 V	-	-	31	-	-	-	ns/V
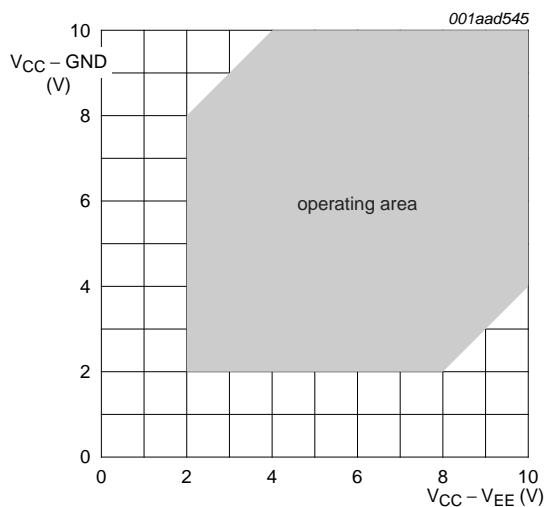
Fig 7. **Guaranteed operating area as a function of the supply voltages for 74HC4053-Q100**
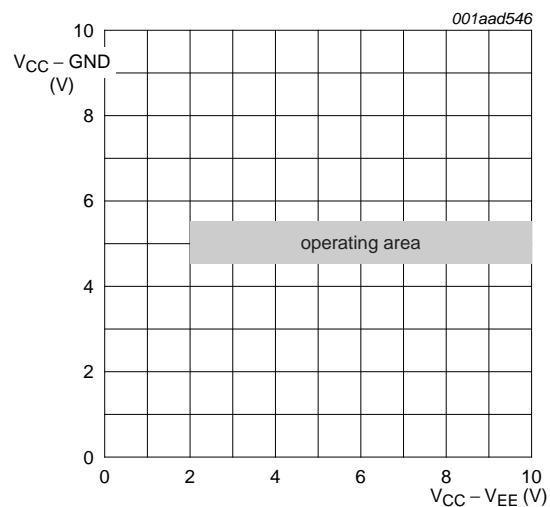
Fig 8. **Guaranteed operating area as a function of the supply voltages for 74HCT4053-Q100**

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10. Static characteristics

Table 6. R_{ON} resistance per switch for 74HC4053-Q100 and 74HCT4053-Q100

$V_I = V_{IH}$ or V_{IL}; for test circuit see Figure 9*.*
V_{is} is the input voltage at a nYn or nZ terminal, whichever is assigned as an input.
V_{os} is the output voltage at a nYn or nZ terminal, whichever is assigned as an output.
For 74HC4053-Q100: $V_{CC} - GND$ or $V_{CC} - V_{EE} = 2.0$ V, 4.5 V, 6.0 V and 9.0 V.
For 74HCT4053-Q100: $V_{CC} - GND = 4.5$ V and 5.5 V, $V_{CC} - V_{EE} = 2.0$ V, 4.5 V, 6.0 V and 9.0 V.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
T_{amb} = 25 °C							
$R_{ON(peak)}$	ON resistance (peak)	$V_{is} = V_{CC}$ to V_{EE}					
		$V_{CC} = 2.0$ V; $V_{EE} = 0$ V; $I_{SW} = 100$ μA	[1]	-	-	-	Ω
		$V_{CC} = 4.5$ V; $V_{EE} = 0$ V; $I_{SW} = 1000$ μA		-	100	180	Ω
		$V_{CC} = 6.0$ V; $V_{EE} = 0$ V; $I_{SW} = 1000$ μA		-	90	160	Ω
		$V_{CC} = 4.5$ V; $V_{EE} = -4.5$ V; $I_{SW} = 1000$ μA		-	70	130	Ω
$R_{ON(rail)}$	ON resistance (rail)	$V_{is} = V_{EE}$					
		$V_{CC} = 2.0$ V; $V_{EE} = 0$ V; $I_{SW} = 100$ μA	[1]	-	150	-	Ω
		$V_{CC} = 4.5$ V; $V_{EE} = 0$ V; $I_{SW} = 1000$ μA		-	80	140	Ω
		$V_{CC} = 6.0$ V; $V_{EE} = 0$ V; $I_{SW} = 1000$ μA		-	70	120	Ω
		$V_{CC} = 4.5$ V; $V_{EE} = -4.5$ V; $I_{SW} = 1000$ μA		-	60	105	Ω
		$V_{is} = V_{CC}$					
		$V_{CC} = 2.0$ V; $V_{EE} = 0$ V; $I_{SW} = 100$ μA	[1]	-	150	-	Ω
		$V_{CC} = 4.5$ V; $V_{EE} = 0$ V; $I_{SW} = 1000$ μA		-	90	160	Ω
		$V_{CC} = 6.0$ V; $V_{EE} = 0$ V; $I_{SW} = 1000$ μA		-	80	140	Ω
		$V_{CC} = 4.5$ V; $V_{EE} = -4.5$ V; $I_{SW} = 1000$ μA		-	65	120	Ω
ΔR_{ON}	ON resistance mismatch between channels	$V_{is} = V_{CC}$ to V_{EE}					
		$V_{CC} = 2.0$ V; $V_{EE} = 0$ V	[1]	-	-	-	Ω
		$V_{CC} = 4.5$ V; $V_{EE} = 0$ V		-	9	-	Ω
		$V_{CC} = 6.0$ V; $V_{EE} = 0$ V		-	8	-	Ω
		$V_{CC} = 4.5$ V; $V_{EE} = -4.5$ V		-	6	-	Ω
T_{amb} = -40 °C to +85 °C							
$R_{ON(peak)}$	ON resistance (peak)	$V_{is} = V_{CC}$ to V_{EE}					
		$V_{CC} = 2.0$ V; $V_{EE} = 0$ V; $I_{SW} = 100$ μA	[1]	-	-	-	Ω
		$V_{CC} = 4.5$ V; $V_{EE} = 0$ V; $I_{SW} = 1000$ μA		-	-	225	Ω
		$V_{CC} = 6.0$ V; $V_{EE} = 0$ V; $I_{SW} = 1000$ μA		-	-	200	Ω
		$V_{CC} = 4.5$ V; $V_{EE} = -4.5$ V; $I_{SW} = 1000$ μA		-	-	165	Ω

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Table 6. **R_{ON} resistance per switch for 74HC4053-Q100 and 74HCT4053-Q100** *…continued*

$V_I = V_{IH}$ or V_{IL}; for test circuit see Figure 9.
V_{is} is the input voltage at a nYn or nZ terminal, whichever is assigned as an input.
*V_{os} is the output voltage at a nYn or nZ terminal, whichever is assigned as an output.*
For 74HC4053-Q100: $V_{CC} - GND$ or $V_{CC} - V_{EE} = 2.0$ V, 4.5 V, 6.0 V and 9.0 V.
For 74HCT4053-Q100: $V_{CC} - GND = 4.5$ V and 5.5 V, $V_{CC} - V_{EE} = 2.0$ V, 4.5 V, 6.0 V and 9.0 V.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{ON(rail)}$	ON resistance (rail)	$V_{is} = V_{EE}$				
		$V_{CC} = 2.0$ V; $V_{EE} = 0$ V; $I_{SW} = 100$ μA [1]	-	-	-	Ω
		$V_{CC} = 4.5$ V; $V_{EE} = 0$ V; $I_{SW} = 1000$ μA	-	-	175	Ω
		$V_{CC} = 6.0$ V; $V_{EE} = 0$ V; $I_{SW} = 1000$ μA	-	-	150	Ω
		$V_{CC} = 4.5$ V; $V_{EE} = -4.5$ V; $I_{SW} = 1000$ μA	-	-	130	Ω
		$V_{is} = V_{CC}$				
		$V_{CC} = 2.0$ V; $V_{EE} = 0$ V; $I_{SW} = 100$ μA [1]	-	-	-	Ω
		$V_{CC} = 4.5$ V; $V_{EE} = 0$ V; $I_{SW} = 1000$ μA	-	-	200	Ω
		$V_{CC} = 6.0$ V; $V_{EE} = 0$ V; $I_{SW} = 1000$ μA	-	-	175	Ω
		$V_{CC} = 4.5$ V; $V_{EE} = -4.5$ V; $I_{SW} = 1000$ μA	-	-	150	Ω
$T_{amb} = -40$ °C to +125 °C						
$R_{ON(peak)}$	ON resistance (peak)	$V_{is} = V_{CC}$ to V_{EE}				
		$V_{CC} = 2.0$ V; $V_{EE} = 0$ V; $I_{SW} = 100$ μA [1]	-	-	-	Ω
		$V_{CC} = 4.5$ V; $V_{EE} = 0$ V; $I_{SW} = 1000$ μA	-	-	270	Ω
		$V_{CC} = 6.0$ V; $V_{EE} = 0$ V; $I_{SW} = 1000$ μA	-	-	240	Ω
		$V_{CC} = 4.5$ V; $V_{EE} = -4.5$ V; $I_{SW} = 1000$ μA	-	-	195	Ω
$R_{ON(rail)}$	ON resistance (rail)	$V_{is} = V_{EE}$				
		$V_{CC} = 2.0$ V; $V_{EE} = 0$ V; $I_{SW} = 100$ μA [1]	-	-	-	Ω
		$V_{CC} = 4.5$ V; $V_{EE} = 0$ V; $I_{SW} = 1000$ μA	-	-	210	Ω
		$V_{CC} = 6.0$ V; $V_{EE} = 0$ V; $I_{SW} = 1000$ μA	-	-	180	Ω
		$V_{CC} = 4.5$ V; $V_{EE} = -4.5$ V; $I_{SW} = 1000$ μA	-	-	160	Ω
		$V_{is} = V_{CC}$				
		$V_{CC} = 2.0$ V; $V_{EE} = 0$ V; $I_{SW} = 100$ μA [1]	-	-	-	Ω
		$V_{CC} = 4.5$ V; $V_{EE} = 0$ V; $I_{SW} = 1000$ μA	-	-	240	Ω
		$V_{CC} = 6.0$ V; $V_{EE} = 0$ V; $I_{SW} = 1000$ μA	-	-	210	Ω
		$V_{CC} = 4.5$ V; $V_{EE} = -4.5$ V; $I_{SW} = 1000$ μA	-	-	180	Ω

[1] When supply voltages ($V_{CC} - V_{EE}$) near 2.0 V the analog switch ON resistance becomes extremely non-linear. When using a supply of 2 V, only use these devices for transmitting digital signals.

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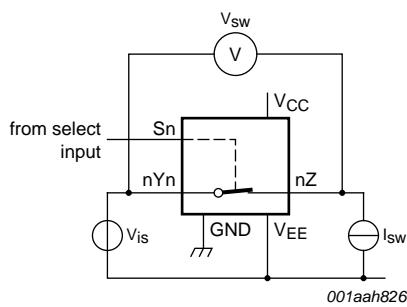
$V_{is} = 0$ V to $(V_{CC} - V_{EE})$.

$$R_{ON} = \frac{V_{sw}}{I_{sw}}$$

Fig 9. Test circuit for measuring R_{ON}
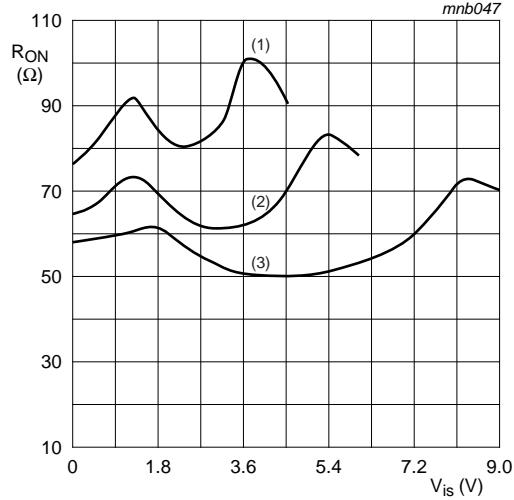
$V_{is} = 0$ V to $(V_{CC} - V_{EE})$.

(1) $V_{CC} = 4.5$ V

(2) $V_{CC} = 6$ V

(3) $V_{CC} = 9$ V

Fig 10. Typical R_{ON} as a function of input voltage V_{is}

Table 7. Static characteristics for 74HC4053-Q100

Voltages are referenced to GND (ground = 0 V).
V_{is} is the input voltage at pins nYn or nZ, whichever is assigned as an input.
V_{os} is the output voltage at pins nZ or nYn, whichever is assigned as an output.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
T_{amb} = 25 °C						
V_{IH}	HIGH-level input voltage	$V_{CC} = 2.0$ V	1.5	1.2	-	V
		$V_{CC} = 4.5$ V	3.15	2.4	-	V
		$V_{CC} = 6.0$ V	4.2	3.2	-	V
		$V_{CC} = 9.0$ V	6.3	4.7	-	V
V_{IL}	LOW-level input voltage	$V_{CC} = 2.0$ V	-	0.8	0.5	V
		$V_{CC} = 4.5$ V	-	2.1	1.35	V
		$V_{CC} = 6.0$ V	-	2.8	1.8	V
		$V_{CC} = 9.0$ V	-	4.3	2.7	V
I_I	input leakage current	$V_{EE} = 0$ V; $V_I = V_{CC}$ or GND				
		$V_{CC} = 6.0$ V	-	-	±0.1	μA
		$V_{CC} = 10.0$ V	-	-	±0.2	μA
$I_{S(OFF)}$	OFF-state leakage current	$V_{CC} = 10.0$ V; $V_{EE} = 0$ V; $V_I = V_{IH}$ or V_{IL}; $\|V_{SW}\| = V_{CC} - V_{EE}$; see [Figure 11]				
		per channel	-	-	±0.1	μA
		all channels	-	-	±0.1	μA
$I_{S(ON)}$	ON-state leakage current	$V_I = V_{IH}$ or V_{IL}; $\|V_{SW}\| = V_{CC} - V_{EE}$; $V_{CC} = 10.0$ V; $V_{EE} = 0$ V; see [Figure 12]	-	-	±0.1	μA

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Table 7. **Static characteristics for 74HC4053-Q100** *…continued*

Voltages are referenced to GND (ground = 0 V).

V_{is} is the input voltage at pins nYn or nZ, whichever is assigned as an input.

V_{os} is the output voltage at pins nZ or nYn, whichever is assigned as an output.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_{CC}	supply current	V_{EE} = 0 V; V_I = V_{CC} or GND; V_{is} = V_{EE} or V_{CC}; V_{os} = V_{CC} or V_{EE}				
		V_{CC} = 6.0 V	-	-	8.0	µA
		V_{CC} = 10.0 V	-	-	16.0	µA
C_I	input capacitance		-	3.5	-	pF
C_{sw}	switch capacitance	independent pins nYn	-	5	-	pF
		common pins nZ	-	8	-	pF
T_{amb} = −40 °C to +85 °C						
V_{IH}	HIGH-level input voltage	V_{CC} = 2.0 V	1.5	-	-	V
		V_{CC} = 4.5 V	3.15	-	-	V
		V_{CC} = 6.0 V	4.2	-	-	V
		V_{CC} = 9.0 V	6.3	-	-	V
V_{IL}	LOW-level input voltage	V_{CC} = 2.0 V	-	-	0.5	V
		V_{CC} = 4.5 V	-	-	1.35	V
		V_{CC} = 6.0 V	-	-	1.8	V
		V_{CC} = 9.0 V	-	-	2.7	V
I_I	input leakage current	V_{EE} = 0 V; V_I = V_{CC} or GND				
		V_{CC} = 6.0 V	-	-	±1.0	µA
		V_{CC} = 10.0 V	-	-	±2.0	µA
$I_{S(OFF)}$	OFF-state leakage current	V_{CC} = 10.0 V; V_{EE} = 0 V; V_I = V_{IH} or V_{IL}; $|V_{SW}|$ = V_{CC} − V_{EE}; see Figure 11				
		per channel	-	-	±1.0	µA
		all channels	-	-	±1.0	µA
$I_{S(ON)}$	ON-state leakage current	V_I = V_{IH} or V_{IL}; $|V_{SW}|$ = V_{CC} − V_{EE}; V_{CC} = 10.0 V; V_{EE} = 0 V; see Figure 12	-	-	±1.0	µA
I_{CC}	supply current	V_{EE} = 0 V; V_I = V_{CC} or GND; V_{is} = V_{EE} or V_{CC}; V_{os} = V_{CC} or V_{EE}				
		V_{CC} = 6.0 V	-	-	80.0	µA
		V_{CC} = 10.0 V	-	-	160.0	µA
T_{amb} = −40 °C to +125 °C						
V_{IH}	HIGH-level input voltage	V_{CC} = 2.0 V	1.5	-	-	V
		V_{CC} = 4.5 V	3.15	-	-	V
		V_{CC} = 6.0 V	4.2	-	-	V
		V_{CC} = 9.0 V	6.3	-	-	V
V_{IL}	LOW-level input voltage	V_{CC} = 2.0 V	-	-	0.5	V
		V_{CC} = 4.5 V	-	-	1.35	V
		V_{CC} = 6.0 V	-	-	1.8	V
		V_{CC} = 9.0 V	-	-	2.7	V

Table 7.   Static characteristics for 74HC4053-Q100 *…continued*

Voltages are referenced to GND (ground = 0 V).

V_{is} is the input voltage at pins nYn or nZ, whichever is assigned as an input.

V_{os} is the output voltage at pins nZ or nYn, whichever is assigned as an output.

| Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_I	input leakage current	$V_{EE} = 0$ V; $V_I = V_{CC}$ or GND				
		$V_{CC} = 6.0$ V	-	-	±1.0	µA
		$V_{CC} = 10.0$ V	-	-	±2.0	µA
$I_{S(OFF)}$	OFF-state leakage current	$V_{CC} = 10.0$ V; $V_{EE} = 0$ V; $V_I = V_{IH}$ or V_{IL}; $|V_{SW}| = V_{CC} - V_{EE}$; see Figure 11				
		per channel	-	-	±1.0	µA
		all channels	-	-	±1.0	µA
$I_{S(ON)}$	ON-state leakage current	$V_I = V_{IH}$ or V_{IL}; $|V_{SW}| = V_{CC} - V_{EE}$; $V_{CC} = 10.0$ V; $V_{EE} = 0$ V; see Figure 12	-	-	±1.0	µA
I_{CC}	supply current	$V_{EE} = 0$ V; $V_I = V_{CC}$ or GND; $V_{is} = V_{EE}$ or V_{CC}; $V_{os} = V_{CC}$ or V_{EE}				
		$V_{CC} = 6.0$ V	-	-	160.0	µA
		$V_{CC} = 10.0$ V	-	-	320.0	µA

Table 8.   Static characteristics for 74HCT4053-Q100

Voltages are referenced to GND (ground = 0 V).

V_{is} is the input voltage at pins nYn or nZ, whichever is assigned as an input.

V_{os} is the output voltage at pins nZ or nYn, whichever is assigned as an output.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$T_{amb} = 25$ °C						
V_{IH}	HIGH-level input voltage	$V_{CC} = 4.5$ V to 5.5 V	2.0	1.6	-	V
V_{IL}	LOW-level input voltage	$V_{CC} = 4.5$ V to 5.5 V	-	1.2	0.8	V
I_I	input leakage current	$V_I = V_{CC}$ or GND; $V_{CC} = 5.5$ V; $V_{EE} = 0$ V	-	-	±0.1	µA
$I_{S(OFF)}$	OFF-state leakage current	$V_{CC} = 10.0$ V; $V_{EE} = 0$ V; $V_I = V_{IH}$ or V_{IL}; $|V_{SW}| = V_{CC} - V_{EE}$; see Figure 11				
		per channel	-	-	±0.1	µA
		all channels	-	-	±0.1	µA
$I_{S(ON)}$	ON-state leakage current	$V_{CC} = 10.0$ V; $V_{EE} = 0$ V; $V_I = V_{IH}$ or V_{IL}; $|V_{SW}| = V_{CC} - V_{EE}$; see Figure 12	-	-	±0.1	µA
I_{CC}	supply current	$V_I = V_{CC}$ or GND; $V_{is} = V_{EE}$ or V_{CC}; $V_{os} = V_{CC}$ or V_{EE}				
		$V_{CC} = 5.5$ V; $V_{EE} = 0$ V	-	-	8.0	µA
		$V_{CC} = 5.0$ V; $V_{EE} = -5.0$ V	-	-	16.0	µA
ΔI_{CC}	additional supply current	per input; $V_I = V_{CC} - 2.1$ V; other inputs at V_{CC} or GND; $V_{CC} = 4.5$ V to 5.5 V; $V_{EE} = 0$ V	-	50	180	µA
C_I	input capacitance		-	3.5	-	pF
C_{sw}	switch capacitance	independent pins nYn	-	5	-	pF
		common pins nZ	-	8	-	pF

Table 8. **Static characteristics for 74HCT4053-Q100** …continued

Voltages are referenced to GND (ground = 0 V).

V_{is} is the input voltage at pins nYn or nZ, whichever is assigned as an input.

*V_{os} is the output voltage at pins nZ or nYn, whichever is assigned as an output.*

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
T_{amb} = −40 °C to +85 °C						
V_{IH}	HIGH-level input voltage	V_{CC} = 4.5 V to 5.5 V	2.0	-	-	V
V_{IL}	LOW-level input voltage	V_{CC} = 4.5 V to 5.5 V	-	-	0.8	V
I_I	input leakage current	$V_I = V_{CC}$ or GND; V_{CC} = 5.5 V; V_{EE} = 0 V	-	-	±1.0	µA
$I_{S(OFF)}$	OFF-state leakage current	V_{CC} = 10.0 V; V_{EE} = 0 V; $V_I = V_{IH}$ or V_{IL}; $|V_{SW}| = V_{CC} - V_{EE}$; see Figure 11				
		per channel	-	-	±1.0	µA
		all channels	-	-	±1.0	µA
$I_{S(ON)}$	ON-state leakage current	V_{CC} = 10.0 V; V_{EE} = 0 V; $V_I = V_{IH}$ or V_{IL}; $|V_{SW}| = V_{CC} - V_{EE}$; see Figure 12	-	-	±1.0	µA
I_{CC}	supply current	$V_I = V_{CC}$ or GND; $V_{is} = V_{EE}$ or V_{CC}; $V_{os} = V_{CC}$ or V_{EE}				
		V_{CC} = 5.5 V; V_{EE} = 0 V	-	-	80.0	µA
		V_{CC} = 5.0 V; V_{EE} = −5.0 V	-	-	160.0	µA
ΔI_{CC}	additional supply current	per input; $V_I = V_{CC} - 2.1$ V; other inputs at V_{CC} or GND; V_{CC} = 4.5 V to 5.5 V; V_{EE} = 0 V	-	-	225	µA
T_{amb} = −40 °C to +125 °C						
V_{IH}	HIGH-level input voltage	V_{CC} = 4.5 V to 5.5 V	2.0	-	-	V
V_{IL}	LOW-level input voltage	V_{CC} = 4.5 V to 5.5 V	-	-	0.8	V
I_I	input leakage current	$V_I = V_{CC}$ or GND; V_{CC} = 5.5 V; V_{EE} = 0 V	-	-	±1.0	µA
$I_{S(OFF)}$	OFF-state leakage current	V_{CC} = 10.0 V; V_{EE} = 0 V; $V_I = V_{IH}$ or V_{IL}; $|V_{SW}| = V_{CC} - V_{EE}$; see Figure 11				
		per channel	-	-	±1.0	µA
		all channels	-	-	±1.0	µA
$I_{S(ON)}$	ON-state leakage current	V_{CC} = 10.0 V; V_{EE} = 0 V; $V_I = V_{IH}$ or V_{IL}; $|V_{SW}| = V_{CC} - V_{EE}$; see Figure 12	-	-	±1.0	µA
I_{CC}	supply current	$V_I = V_{CC}$ or GND; $V_{is} = V_{EE}$ or V_{CC}; $V_{os} = V_{CC}$ or V_{EE}				
		V_{CC} = 5.5 V; V_{EE} = 0 V	-	-	160.0	µA
		V_{CC} = 5.0 V; V_{EE} = −5.0 V	-	-	320.0	µA
ΔI_{CC}	additional supply current	per input; $V_I = V_{CC} - 2.1$ V; other inputs at V_{CC} or GND; V_{CC} = 4.5 V to 5.5 V; V_{EE} = 0 V	-	-	245	µA

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$V_{is} = V_{CC}$ and $V_{os} = V_{EE}$.

$V_{is} = V_{EE}$ and $V_{os} = V_{CC}$.

Fig 11. Test circuit for measuring OFF-state current
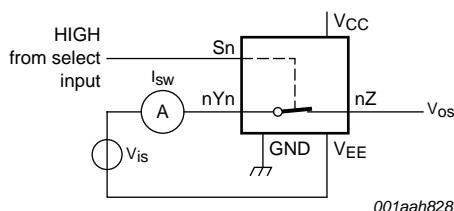
$V_{is} = V_{CC}$ and V_{os} = open-circuit.

$V_{is} = V_{EE}$ and V_{os} = open-circuit.

Fig 12. Test circuit for measuring ON-state current

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11. Dynamic characteristics

Table 9.   Dynamic characteristics for 74HC4053-Q100

GND = 0 V; $t_r = t_f$ = 6 ns; C_L = 50 pF; for test circuit see Figure 15.

V_{is} is the input voltage at a nYn or nZ terminal, whichever is assigned as an input.

V_{os} is the output voltage at a nYn or nZ terminal, whichever is assigned as an output.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
T_{amb} = 25 °C							
t_{pd}	propagation delay	V_{is} to V_{os}; $R_L = \infty \Omega$; see Figure 13	[1]				
		V_{CC} = 2.0 V; V_{EE} = 0 V		-	15	60	ns
		V_{CC} = 4.5 V; V_{EE} = 0 V		-	5	12	ns
		V_{CC} = 6.0 V; V_{EE} = 0 V		-	4	10	ns
		V_{CC} = 4.5 V; V_{EE} = −4.5 V		-	4	8	ns
t_{on}	turn-on time	$\overline{E}$ to V_{os}; $R_L = \infty \Omega$; see Figure 14	[2]				
		V_{CC} = 2.0 V; V_{EE} = 0 V		-	60	220	ns
		V_{CC} = 4.5 V; V_{EE} = 0 V		-	20	44	ns
		V_{CC} = 5.0 V; V_{EE} = 0 V; C_L = 15 pF		-	17	-	ns
		V_{CC} = 6.0 V; V_{EE} = 0 V		-	16	37	ns
		V_{CC} = 4.5 V; V_{EE} = −4.5 V		-	15	31	ns
		Sn to V_{os}; $R_L = \infty \Omega$; see Figure 14	[2]				
		V_{CC} = 2.0 V; V_{EE} = 0 V		-	75	220	ns
		V_{CC} = 4.5 V; V_{EE} = 0 V		-	25	44	ns
		V_{CC} = 5.0 V; V_{EE} = 0 V; C_L = 15 pF		-	21	-	ns
		V_{CC} = 6.0 V; V_{EE} = 0 V		-	20	37	ns
		V_{CC} = 4.5 V; V_{EE} = −4.5 V		-	15	31	ns
t_{off}	turn-off time	$\overline{E}$ to V_{os}; R_L = 1 kΩ; see Figure 14	[3]				
		V_{CC} = 2.0 V; V_{EE} = 0 V		-	63	210	ns
		V_{CC} = 4.5 V; V_{EE} = 0 V		-	21	42	ns
		V_{CC} = 5.0 V; V_{EE} = 0 V; C_L = 15 pF		-	18	-	ns
		V_{CC} = 6.0 V; V_{EE} = 0 V		-	17	36	ns
		V_{CC} = 4.5 V; V_{EE} = −4.5 V		-	15	29	ns
		Sn to V_{os}; R_L = 1 kΩ; see Figure 14	[3]				
		V_{CC} = 2.0 V; V_{EE} = 0 V		-	60	210	ns
		V_{CC} = 4.5 V; V_{EE} = 0 V		-	20	42	ns
		V_{CC} = 5.0 V; V_{EE} = 0 V; C_L = 15 pF		-	17	-	ns
		V_{CC} = 6.0 V; V_{EE} = 0 V		-	16	36	ns
		V_{CC} = 4.5 V; V_{EE} = −4.5 V		-	15	29	ns
C_{PD}	power dissipation capacitance	per switch; V_I = GND to V_{CC}	[4]	-	36	-	pF

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Table 9. **Dynamic characteristics for 74HC4053-Q100** *…continued*
GND = 0 V; t_r = t_f = 6 ns; C_L = 50 pF; for test circuit see Figure 15.
V_{is} is the input voltage at a nYn or nZ terminal, whichever is assigned as an input.
V_{os} is the output voltage at a nYn or nZ terminal, whichever is assigned as an output.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
T_{amb} = −40 °C to +85 °C							
t_{pd}	propagation delay	V_{is} to V_{os}; R_L = ∞ Ω; see Figure 13	[1]				
		V_{CC} = 2.0 V; V_{EE} = 0 V		-	-	75	ns
		V_{CC} = 4.5 V; V_{EE} = 0 V		-	-	15	ns
		V_{CC} = 6.0 V; V_{EE} = 0 V		-	-	13	ns
		V_{CC} = 4.5 V; V_{EE} = −4.5 V		-	-	10	ns
t_{on}	turn-on time	$\overline{E}$ to V_{os}; R_L = ∞ Ω; see Figure 14	[2]				
		V_{CC} = 2.0 V; V_{EE} = 0 V		-	-	275	ns
		V_{CC} = 4.5 V; V_{EE} = 0 V		-	-	55	ns
		V_{CC} = 6.0 V; V_{EE} = 0 V		-	-	47	ns
		V_{CC} = 4.5 V; V_{EE} = −4.5 V		-	-	39	ns
		Sn to V_{os}; R_L = ∞ Ω; see Figure 14	[2]				
		V_{CC} = 2.0 V; V_{EE} = 0 V		-	-	275	ns
		V_{CC} = 4.5 V; V_{EE} = 0 V		-	-	55	ns
		V_{CC} = 6.0 V; V_{EE} = 0 V		-	-	47	ns
		V_{CC} = 4.5 V; V_{EE} = −4.5 V		-	-	39	ns
t_{off}	turn-off time	$\overline{E}$ to V_{os}; R_L = 1 kΩ; see Figure 14	[3]				
		V_{CC} = 2.0 V; V_{EE} = 0 V		-	-	265	ns
		V_{CC} = 4.5 V; V_{EE} = 0 V		-	-	53	ns
		V_{CC} = 6.0 V; V_{EE} = 0 V		-	-	45	ns
		V_{CC} = 4.5 V; V_{EE} = −4.5 V		-	-	36	ns
		Sn to V_{os}; R_L = 1 kΩ; see Figure 14	[3]				
		V_{CC} = 2.0 V; V_{EE} = 0 V		-	-	265	ns
		V_{CC} = 4.5 V; V_{EE} = 0 V		-	-	53	ns
		V_{CC} = 6.0 V; V_{EE} = 0 V		-	-	45	ns
		V_{CC} = 4.5 V; V_{EE} = −4.5 V		-	-	36	ns
T_{amb} = −40 °C to +125 °C							
t_{pd}	propagation delay	V_{is} to V_{os}; R_L = ∞ Ω; see Figure 13	[1]				
		V_{CC} = 2.0 V; V_{EE} = 0 V		-	-	90	ns
		V_{CC} = 4.5 V; V_{EE} = 0 V		-	-	18	ns
		V_{CC} = 6.0 V; V_{EE} = 0 V		-	-	15	ns
		V_{CC} = 4.5 V; V_{EE} = −4.5 V		-	-	12	ns

Table 9.   **Dynamic characteristics for 74HC4053-Q100** …*continued*
GND = 0 V; t_r = t_f = 6 ns; C_L = 50 pF; for test circuit see Figure 15.
V_{is} is the input voltage at a nYn or nZ terminal, whichever is assigned as an input.
V_{os} is the output voltage at a nYn or nZ terminal, whichever is assigned as an output.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
t_{on}	turn-on time	$\overline{E}$ to V_{os}; R_L = ∞ Ω; see Figure 14	[2]				
		V_{CC} = 2.0 V; V_{EE} = 0 V		-	-	330	ns
		V_{CC} = 4.5 V; V_{EE} = 0 V		-	-	66	ns
		V_{CC} = 6.0 V; V_{EE} = 0 V		-	-	56	ns
		V_{CC} = 4.5 V; V_{EE} = −4.5 V		-	-	47	ns
		Sn to V_{os}; R_L = ∞ Ω; see Figure 14	[2]				
		V_{CC} = 2.0 V; V_{EE} = 0 V		-	-	330	ns
		V_{CC} = 4.5 V; V_{EE} = 0 V		-	-	66	ns
		V_{CC} = 6.0 V; V_{EE} = 0 V		-	-	56	ns
		V_{CC} = 4.5 V; V_{EE} = −4.5 V		-	-	47	ns
t_{off}	turn-off time	$\overline{E}$ to V_{os}; R_L = 1 kΩ; see Figure 14	[3]				
		V_{CC} = 2.0 V; V_{EE} = 0 V		-	-	315	ns
		V_{CC} = 4.5 V; V_{EE} = 0 V		-	-	63	ns
		V_{CC} = 6.0 V; V_{EE} = 0 V		-	-	54	ns
		V_{CC} = 4.5 V; V_{EE} = −4.5 V		-	-	44	ns
		Sn to V_{os}; R_L = 1 kΩ; see Figure 14	[3]				
		V_{CC} = 2.0 V; V_{EE} = 0 V		-	-	315	ns
		V_{CC} = 4.5 V; V_{EE} = 0 V		-	-	63	ns
		V_{CC} = 6.0 V; V_{EE} = 0 V		-	-	54	ns
		V_{CC} = 4.5 V; V_{EE} = −4.5 V		-	-	44	ns

[1] t_{pd} is the same as t_{PHL} and t_{PLH}.

[2] t_{on} is the same as $t_{PZH \, and} \, t_{PZL}$.

[3] t_{off} is the same as t_{PHZ} and t_{PLZ}.

[4] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma\{(C_L + C_{sw}) \times V_{CC}^2 \times f_o\}$ where:

f_i = input frequency in MHz;

f_o = output frequency in MHz;

N = number of inputs switching;

$\Sigma\{(C_L + C_{sw}) \times V_{CC}^2 \times f_o\}$ = sum of outputs;

C_L = output load capacitance in pF;

C_{sw} = switch capacitance in pF;

V_{CC} = supply voltage in V.

Table 10. **Dynamic characteristics for 74HCT4053-Q100**

GND = 0 V; t_r = t_f = 6 ns; C_L = 50 pF; for test circuit see Figure 15.
V_{is} is the input voltage at a nYn or nZ terminal, whichever is assigned as an input.
V_{os} is the output voltage at a nYn or nZ terminal, whichever is assigned as an output.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
T_{amb} = 25 °C							
t_{pd}	propagation delay	V_{is} to V_{os}; R_L = ∞ Ω; see Figure 13	[1]				
		V_{CC} = 4.5 V; V_{EE} = 0 V		-	5	12	ns
		V_{CC} = 4.5 V; V_{EE} = −4.5 V		-	4	8	ns
t_{on}	turn-on time	$\overline{E}$ to V_{os}; R_L = 1 kΩ; see Figure 14	[2]				
		V_{CC} = 4.5 V; V_{EE} = 0 V		-	27	48	ns
		V_{CC} = 5.0 V; V_{EE} = 0 V; C_L = 15 pF		-	23	-	ns
		V_{CC} = 4.5 V; V_{EE} = −4.5 V		-	16	34	ns
		Sn to V_{os}; R_L = 1 kΩ; see Figure 14	[2]				
		V_{CC} = 4.5 V; V_{EE} = 0 V		-	25	48	ns
		V_{CC} = 5.0 V; V_{EE} = 0 V; C_L = 15 pF		-	21	-	ns
		V_{CC} = 4.5 V; V_{EE} = −4.5 V		-	16	34	ns
t_{off}	turn-off time	$\overline{E}$ to V_{os}; R_L = 1 kΩ; see Figure 14	[3]				
		V_{CC} = 4.5 V; V_{EE} = 0 V		-	24	44	ns
		V_{CC} = 5.0 V; V_{EE} = 0 V; C_L = 15 pF		-	20	-	ns
		V_{CC} = 4.5 V; V_{EE} = −4.5 V		-	15	31	ns
		Sn to V_{os}; R_L = 1 kΩ; see Figure 14	[3]				
		V_{CC} = 4.5 V; V_{EE} = 0 V		-	22	44	ns
		V_{CC} = 5.0 V; V_{EE} = 0 V; C_L = 15 pF		-	19	-	ns
		V_{CC} = 4.5 V; V_{EE} = −4.5 V		-	15	31	ns
C_{PD}	power dissipation capacitance	per switch; V_I = GND to V_{CC} − 1.5 V	[4]	-	36	-	pF
T_{amb} = −40 °C to +85 °C							
t_{pd}	propagation delay	V_{is} to V_{os}; R_L = ∞ Ω; see Figure 13	[1]				
		V_{CC} = 4.5 V; V_{EE} = 0 V		-	-	15	ns
		V_{CC} = 4.5 V; V_{EE} = −4.5 V		-	-	10	ns
t_{on}	turn-on time	$\overline{E}$ to V_{os}; R_L = 1 kΩ; see Figure 14	[2]				
		V_{CC} = 4.5 V; V_{EE} = 0 V		-	-	60	ns
		V_{CC} = 4.5 V; V_{EE} = −4.5 V		-	-	43	ns
		Sn to V_{os}; R_L = 1 kΩ; see Figure 14	[2]				
		V_{CC} = 4.5 V; V_{EE} = 0 V		-	-	60	ns
		V_{CC} = 4.5 V; V_{EE} = −4.5 V		-	-	43	ns
t_{off}	turn-off time	$\overline{E}$ to V_{os}; R_L = 1 kΩ; see Figure 14	[3]				
		V_{CC} = 4.5 V; V_{EE} = 0 V		-	-	55	ns
		V_{CC} = 4.5 V; V_{EE} = −4.5 V		-	-	39	ns
		Sn to V_{os}; R_L = 1 kΩ; see Figure 14	[3]				
		V_{CC} = 4.5 V; V_{EE} = 0 V		-	-	55	ns
		V_{CC} = 4.5 V; V_{EE} = −4.5 V		-	-	39	ns

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Table 10.   Dynamic characteristics for 74HCT4053-Q100 …*continued*
GND = 0 V; $t_r = t_f$ = 6 ns; C_L = 50 pF; for test circuit see Figure 15.
V_{is} is the input voltage at a nYn or nZ terminal, whichever is assigned as an input.
V_{os} is the output voltage at a nYn or nZ terminal, whichever is assigned as an output.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
T_{amb} = −40 °C to +125 °C							
t_{pd}	propagation delay	V_{is} to V_{os}; R_L = ∞ Ω; see Figure 13	[1]				
		V_{CC} = 4.5 V; V_{EE} = 0 V		-	-	18	ns
		V_{CC} = 4.5 V; V_{EE} = −4.5 V		-	-	12	ns
t_{on}	turn-on time	$\overline{E}$ to V_{os}; R_L = 1 kΩ; see Figure 14	[2]				
		V_{CC} = 4.5 V; V_{EE} = 0 V		-	-	72	ns
		V_{CC} = 4.5 V; V_{EE} = −4.5 V		-	-	51	ns
		Sn to V_{os}; R_L = 1 kΩ; see Figure 14	[2]				
		V_{CC} = 4.5 V; V_{EE} = 0 V		-	-	72	ns
		V_{CC} = 4.5 V; V_{EE} = −4.5 V		-	-	51	ns
t_{off}	turn-off time	$\overline{E}$ to V_{os}; R_L = 1 kΩ; see Figure 14	[3]				
		V_{CC} = 4.5 V; V_{EE} = 0 V		-	-	66	ns
		V_{CC} = 4.5 V; V_{EE} = −4.5 V		-	-	47	ns
		Sn to V_{os}; R_L = 1 kΩ; see Figure 14	[3]				
		V_{CC} = 4.5 V; V_{EE} = 0 V		-	-	66	ns
		V_{CC} = 4.5 V; V_{EE} = −4.5 V		-	-	47	ns

[1] t_{pd} is the same as t_{PHL} and t_{PLH}.

[2] t_{on} is the same as t_{PZH} and t_{PZL}.

[3] t_{off} is the same as t_{PHZ} and t_{PLZ}.

[4] C_{PD} is used to determine the dynamic power dissipation (P_D in µW).

$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma\{(C_L + C_{sw}) \times V_{CC}^2 \times f_o\}$ where:

f_i = input frequency in MHz;

f_o = output frequency in MHz;

N = number of inputs switching;

$\Sigma\{(C_L + C_{sw}) \times V_{CC}^2 \times f_o\}$ = sum of outputs;

C_L = output load capacitance in pF;

C_{sw} = switch capacitance in pF;

V_{CC} = supply voltage in V.

Fig 13.   Input (V_{is}) to output (V_{os}) propagation delays

For 74HC4053-Q100: $V_M = 0.5 \times V_{CC}$.

For 74HCT4053-Q100: $V_M = 1.3$ V.
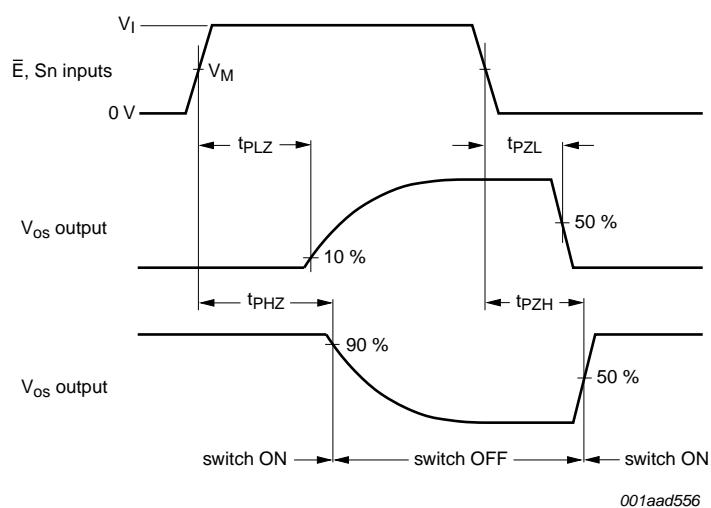
Fig 14. Turn-on and turn-off times
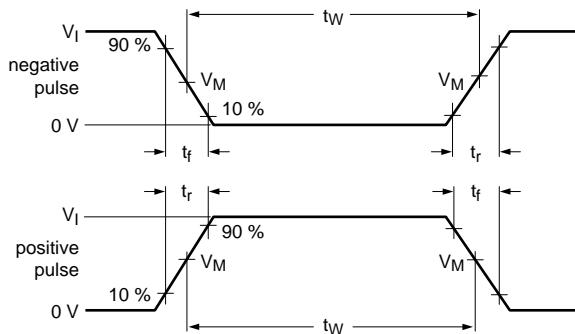
Definitions for test circuit; see Table 11:

R_T = termination resistance should be equal to the output impedance Z_o of the pulse generator.

C_L = load capacitance including jig and probe capacitance.

R_L = load resistance.

S1 = Test selection switch.

Fig 15. Test circuit for measuring switching times

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Table 11.   Test data

Test	Input				Load		S1 position
	V_I	V_{is}	t_r, t_f		C_L	R_L	
			at f_{max}	other[1]			
t_{PHL}, t_{PLH}	[2]	pulse	< 2 ns	6 ns	50 pF	1 kΩ	open
t_{PZH}, t_{PHZ}	[2]	V_{CC}	< 2 ns	6 ns	50 pF	1 kΩ	V_{EE}
t_{PZL}, t_{PLZ}	[2]	V_{EE}	< 2 ns	6 ns	50 pF	1 kΩ	V_{CC}

[1] t_r = t_f = 6 ns; when measuring f_{max}, there is no constraint to t_r and t_f with 50 % duty factor.

[2] V_I values:

      a) For 74HC4053-Q100: V_I = V_{CC}

      b) For 74HCT4053-Q100: V_I = 3 V

11.1   Additional dynamic characteristics

Table 12.   Additional dynamic characteristics
Recommended conditions and typical values; GND = 0 V; T_{amb} = 25 °C; C_L = 50 pF.
V_{is} is the input voltage at pins nYn or nZ, whichever is assigned as an input.
V_{os} is the output voltage at pins nYn or nZ, whichever is assigned as an output.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
d_{sin}	sine-wave distortion	f_i = 1 kHz; R_L = 10 kΩ; see Figure 16				
		V_{is} = 4.0 V (p-p); V_{CC} = 2.25 V; V_{EE} = −2.25 V	-	0.04	-	%
		V_{is} = 8.0 V (p-p); V_{CC} = 4.5 V; V_{EE} = −4.5 V	-	0.02	-	%
		f_i = 10 kHz; R_L = 10 kΩ; see Figure 16				
		V_{is} = 4.0 V (p-p); V_{CC} = 2.25 V; V_{EE} = −2.25 V	-	0.12	-	%
		V_{is} = 8.0 V (p-p); V_{CC} = 4.5 V; V_{EE} = −4.5 V	-	0.06	-	%
α_{iso}	isolation (OFF-state)	R_L = 600 Ω; f_i = 1 MHz; see Figure 17				
		V_{CC} = 2.25 V; V_{EE} = −2.25 V	[1] -	−50	-	dB
		V_{CC} = 4.5 V; V_{EE} = −4.5 V	[1] -	−50	-	dB
Xtalk	crosstalk	between two switches/multiplexers; R_L = 600 Ω; f_i = 1 MHz; see Figure 18				
		V_{CC} = 2.25 V; V_{EE} = −2.25 V	[1] -	−60	-	dB
		V_{CC} = 4.5 V; V_{EE} = −4.5 V	[1] -	−60	-	dB
V_{ct}	crosstalk voltage	peak-to-peak value between control and any switch. R_L = 600 Ω; f_i = 1 MHz; $\overline{E}$ or Sn square wave between V_{CC} and GND; t_r = t_f = 6 ns; see Figure 19				
		V_{CC} = 4.5 V; V_{EE} = 0 V	-	110	-	mV
		V_{CC} = 4.5 V; V_{EE} = −4.5 V	-	220	-	mV
$f_{(−3dB)}$	−3 dB frequency response	R_L = 50 Ω; see Figure 20				
		V_{CC} = 2.25 V; V_{EE} = −2.25 V	[2] -	160	-	MHz
		V_{CC} = 4.5 V; V_{EE} = −4.5 V	[2] -	170	-	MHz

[1]   Adjust input voltage V_{is} to 0 dBm level (0 dBm = 1 mW into 600 Ω).

[2]   Adjust input voltage V_{is} to 0 dBm level at V_{os} for 1 MHz (0 dBm = 1 mW into 50 Ω).
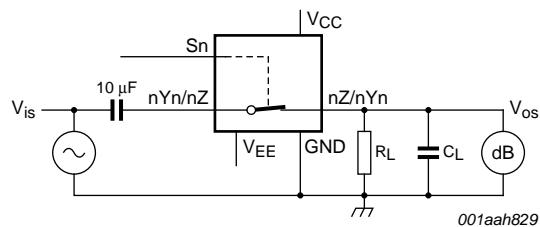
Fig 16. Test circuit for measuring sine-wave distortion
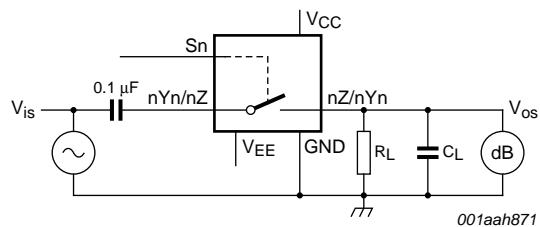

V_{CC} = 4.5 V; GND = 0 V; V_{EE} = −4.5 V; R_L = 600 Ω; R_S = 1 kΩ.
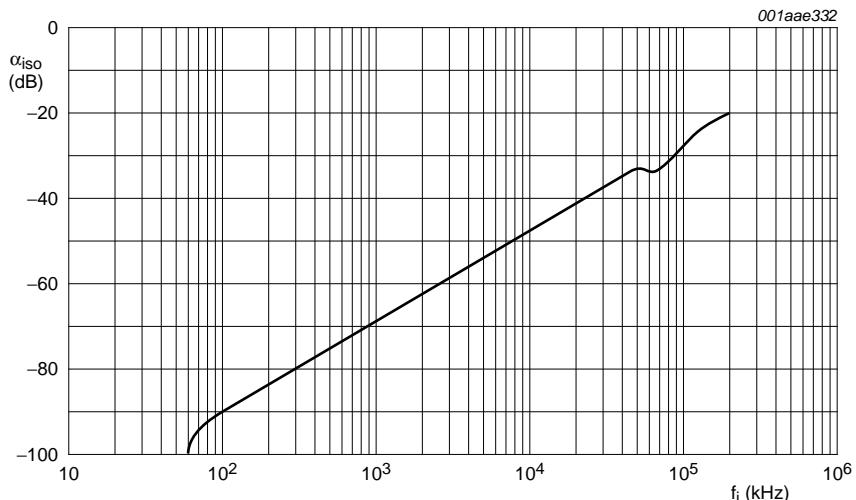
a. Test circuit

b. Isolation (OFF-state) as a function of frequency

Fig 17. Test circuit for measuring isolation (OFF-state)
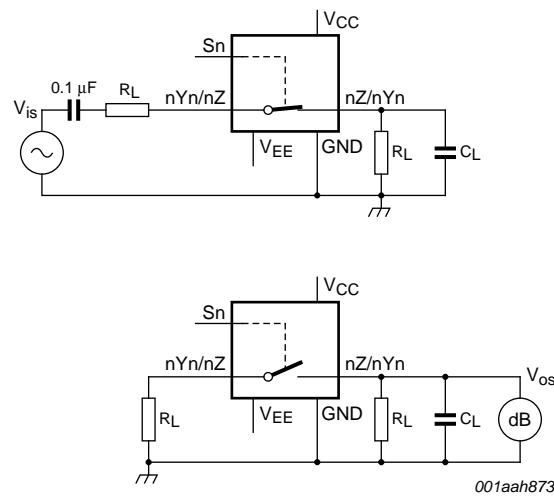
Fig 18.   Test circuits for measuring crosstalk between any two switches/multiplexers
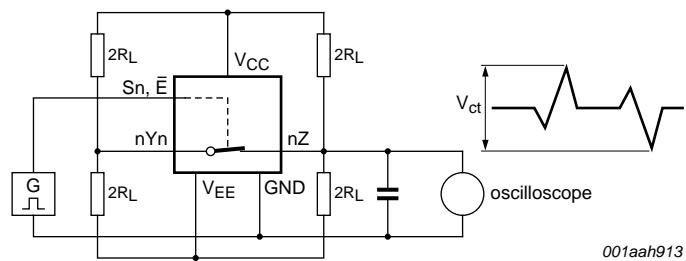
Fig 19.   Test circuit for measuring crosstalk between control input and any switch

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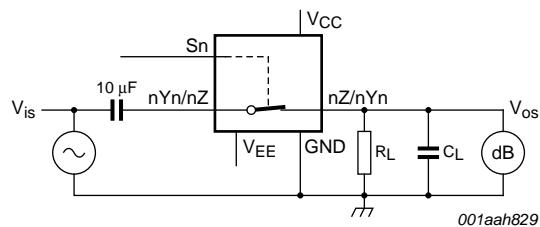
V_{CC} = 4.5 V; GND = 0 V; V_{EE} = −4.5 V; R_L = 50 Ω; R_S = 1 kΩ.
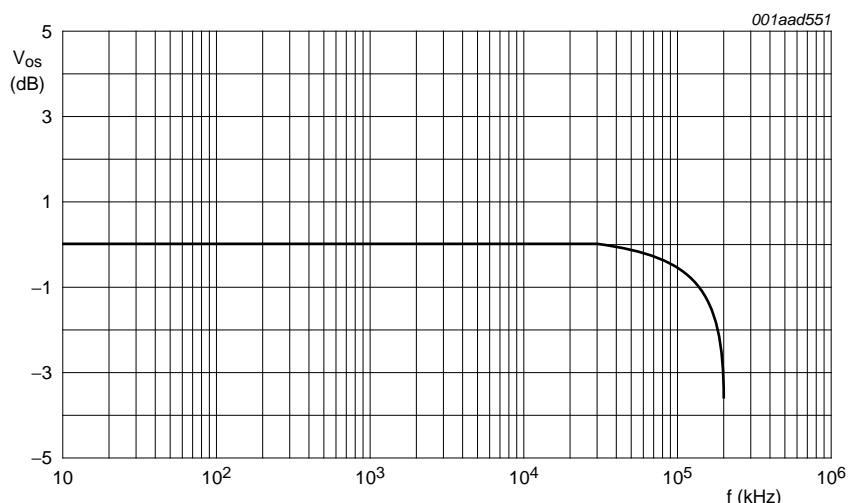
a. Test circuit

b. Typical frequency response

Fig 20. Test circuit for frequency response

12. Package outline

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1
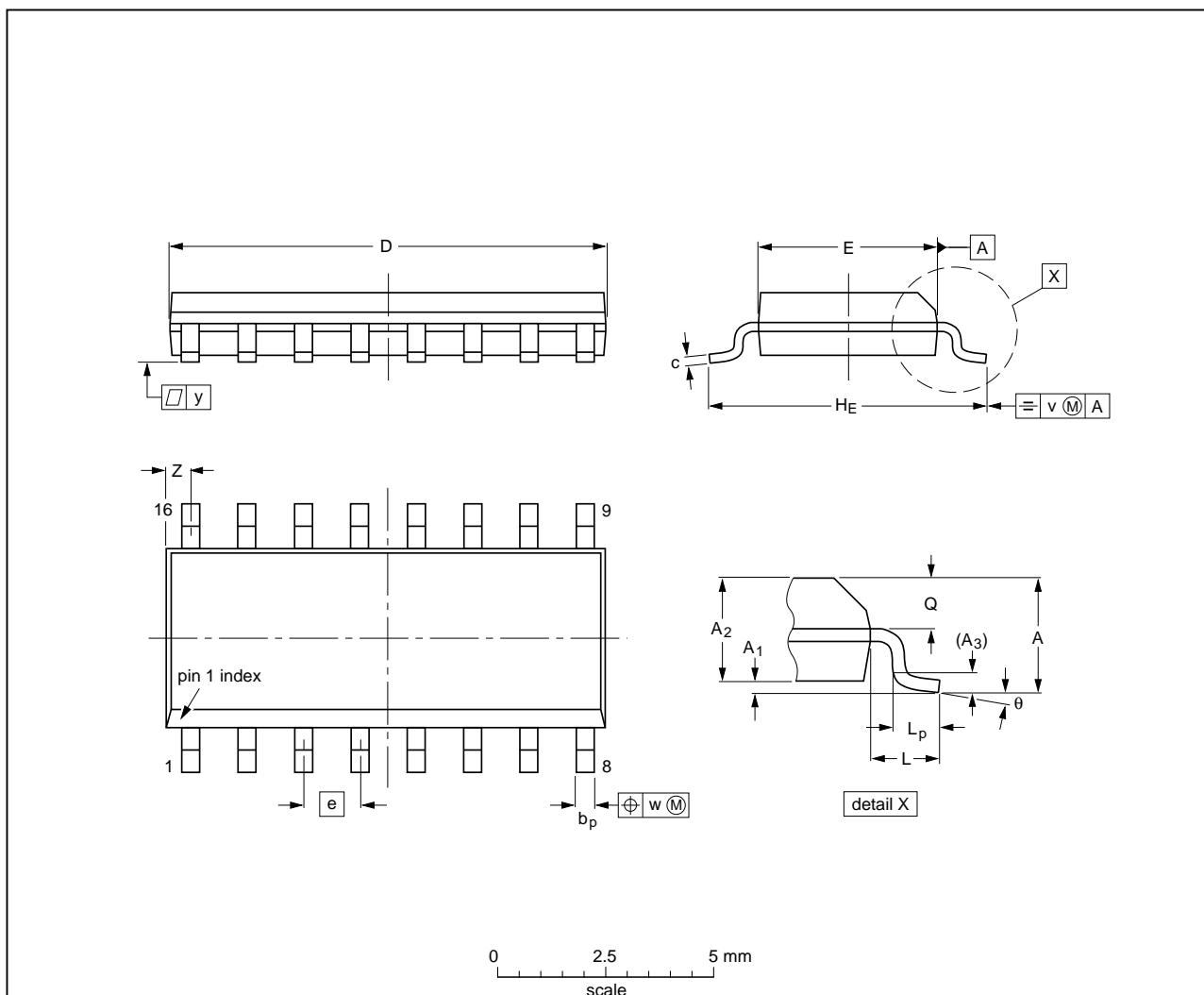
DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A₁	A₂	A₃	bₚ	c	D[1]	E[1]	e	H_E	L	Lₚ	Q	v	w	y	Z[1]	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	10.0 9.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.39 0.38	0.16 0.15	0.05	0.244 0.228	0.041	0.039 0.016	0.028 0.020	0.01	0.01	0.004	0.028 0.012	

Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT109-1	076E07	MS-012				~~99-12-27~~ 03-02-19

Fig 21. Package outline SOT109-1 (SO16)

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TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm

SOT403-1

DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D [1]	E [2]	e	H_E	L	L_p	Q	v	w	y	Z [1]	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.40 0.06	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT403-1		MO-153				~~99-12-27~~ 03-02-18

Fig 22. Package outline SOT403-1 (TSSOP16)

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DHVQFN16: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 16 terminals; body 2.5 x 3.5 x 0.85 mm

SOT763-1

DIMENSIONS (mm are the original dimensions)

UNIT	A[1] max.	A₁	b	c	D[1]	Dₕ	E[1]	Eₕ	e	e₁	L	v	w	y	y₁
mm	1	0.05 0.00	0.30 0.18	0.2	3.6 3.4	2.15 1.85	2.6 2.4	1.15 0.85	0.5	2.5	0.5 0.3	0.1	0.05	0.05	0.1

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT763-1	- - -	MO-241	- - -			~~02-10-17~~ 03-01-27
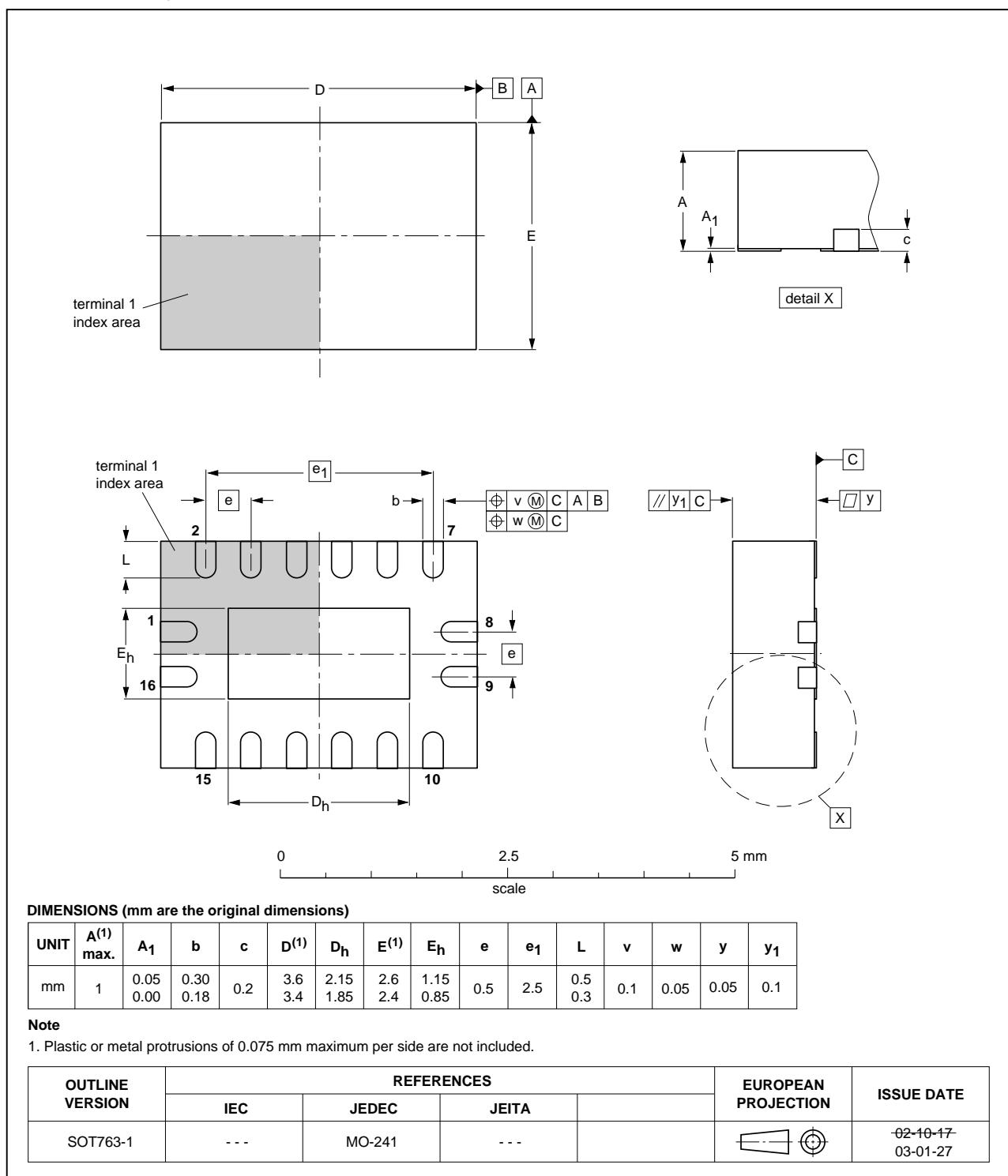
Fig 23. Package outline SOT763-1 (DHVQFN16)

13. Abbreviations

Table 13.   Abbreviations

Acronym	Description
CMOS	Complementary Metal-Oxide Semiconductor
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
MIL	Military

14. Revision history

Table 14.   Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT4053_Q100 v.2	20121122	Product data sheet	-	74HC_HCT4053_Q100 v.1
Modifications:	• CDM added to features.			
74HC_HCT4053_Q100 v.1	20120720	Product data sheet	-	-

15. Legal information

15.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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17. Contents

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Document identifier: 74HC_HCT4053_Q100